

Description

The 15N06 is the high cell density trench N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

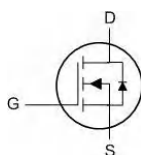
The 15N06 meet the RoHS and Green Product

Features

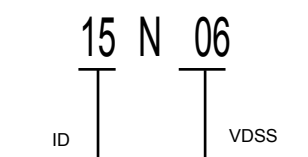
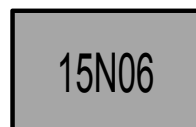
Green Device Available
Super Low Gate Charge
Excellent CdV/dt effect decline
Advanced high cell density Trench technology

V_{DS} 60 V
 I_D 15 A
 $R_{DS(ON)}$ 26 m Ω

Equivalent Circuit



SOT-89-3L top view



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	15	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	7.5	A
I_{DM}	Pulsed Drain Current ²	22	A
EAS	Single Pulse Avalanche Energy ³	22	mJ
I_{AS}	Avalanche Current	23	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ⁴	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	85	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	25	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted.)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} = 0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =5A	-	26	40	mΩ
		V _{GS} =4.5V, I _D =3A	-	35	50	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	1148	-	pF
C _{oss}	Output Capacitance		-	58.5	-	pF
C _{rss}	Reverse Transfer Capacitance		-	49.4	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =2.5A, V _{GS} =10V	-	20.3	-	nC
Q _{gs}	Gate-Source Charge		-	3.7	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	5.3	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =30V, I _D =5A, R _G =1.8Ω, V _{GS} =10V	-	7.6	-	ns
t _r	Turn-on Rise Time		-	20	-	ns
t _{d(off)}	Turn-off Delay Time		-	15	-	ns
t _f	Turn-off Fall Time		-	24	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	5	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	20	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =5A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F =5A, dI/dt=100A/μs	-	29	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	43	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ C, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=8.7A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

RATING AND CHARACTERISTIC CURVES

Figure1: Output Characteristics

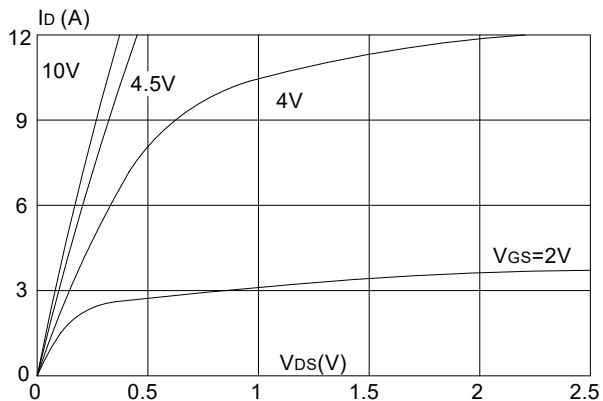


Figure 2: Typical Transfer Characteristics

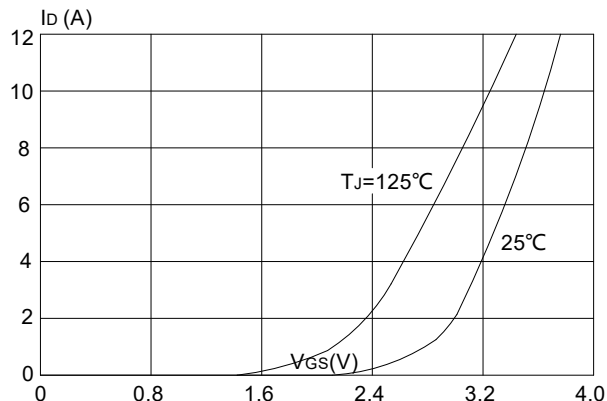


Figure 3: On-resistance vs. Drain Current

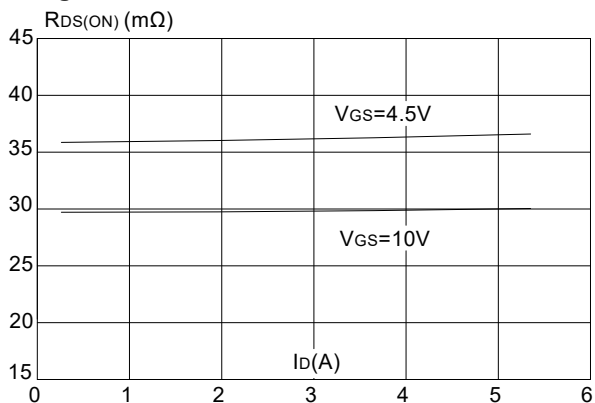


Figure 4: Body Diode Characteristics

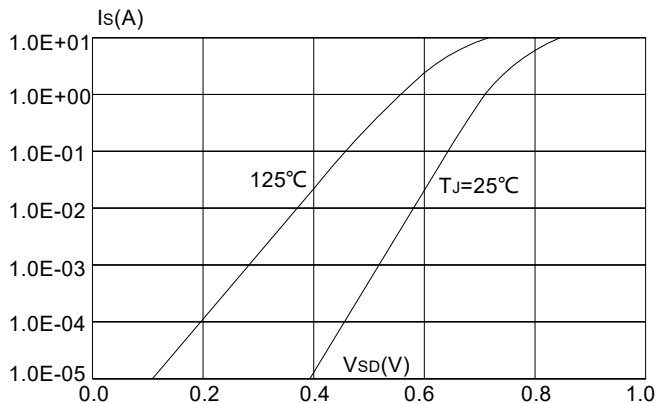


Figure 5: Gate Charge Characteristics

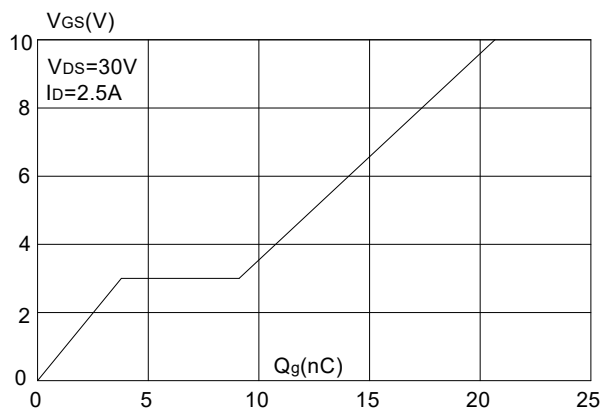
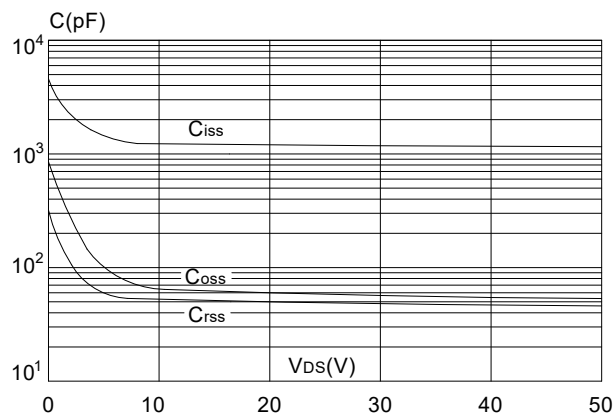


Figure 6: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

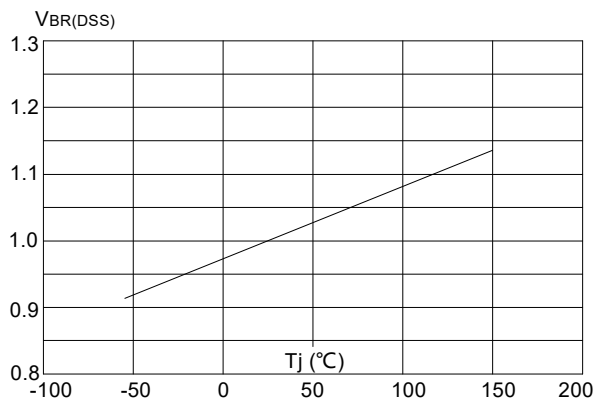


Figure 8: Normalized on Resistance vs. Junction Temperature

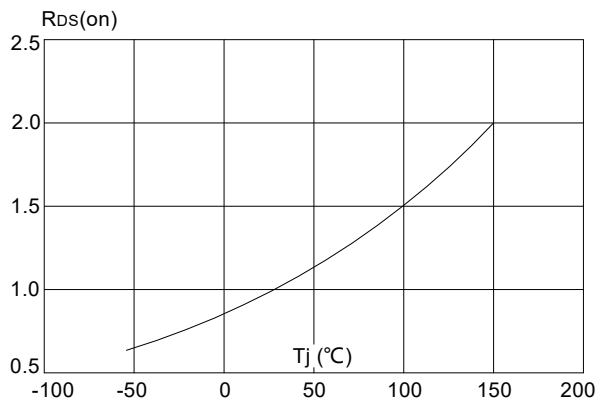


Figure 9: Maximum Safe Operating Area

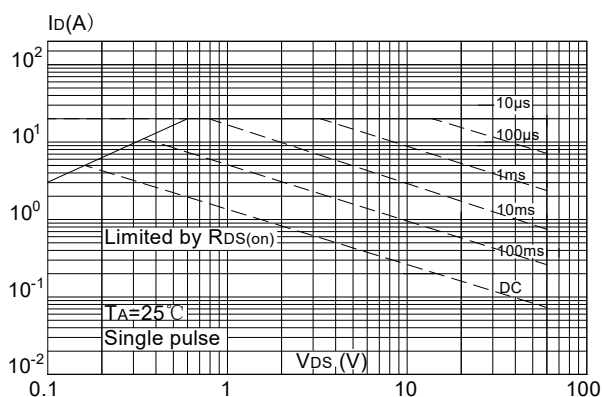


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

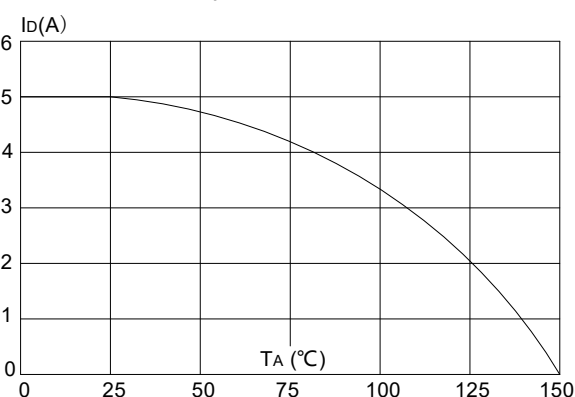
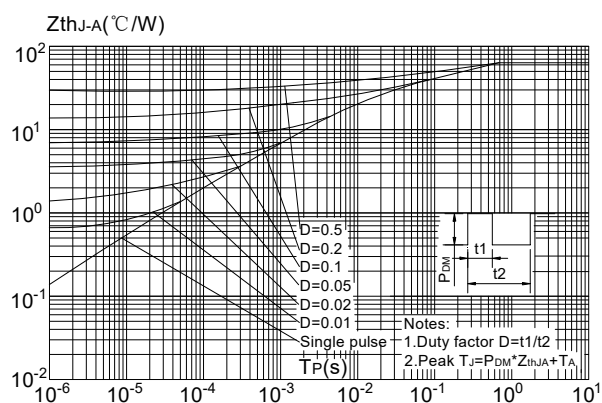
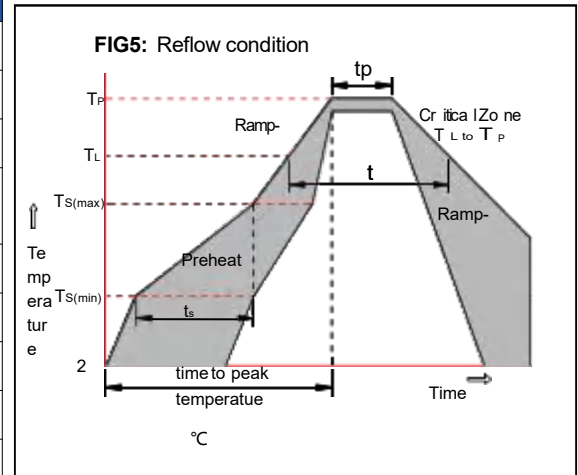


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



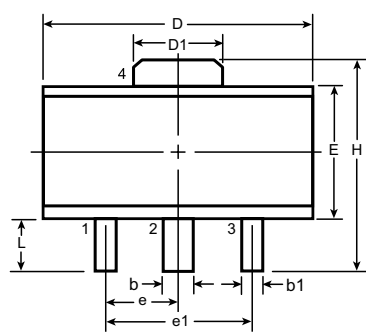
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

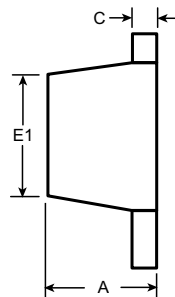


Package Dimensions & Suggested Pad Layout

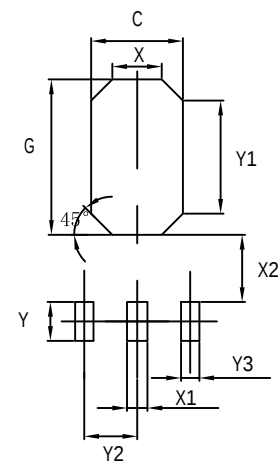
SOT89



Top View



Side View

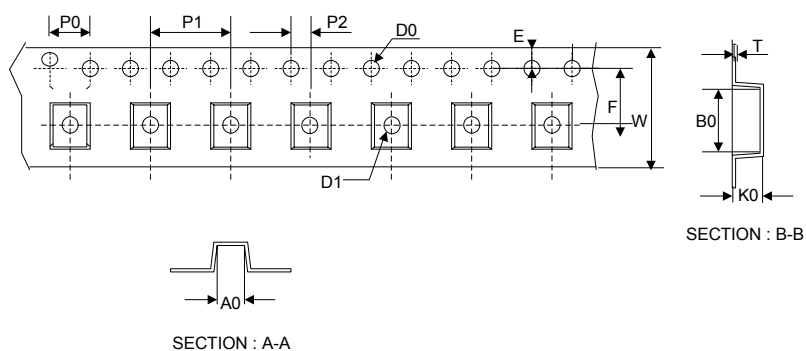


Symbol	A	b	b1	C	D	D1	E	E1	e	e1	H	L
MIN	1.40	0.44	0.36	0.3	4.40	1.50	2.29	2.00*	1.50	3.00	3.94	0.89
NOM	-	-	-	-	-	-	-	-	-	-	-	-
MAX	1.60	0.56	0.48	0.5	4.60	1.75	2.60	2.29	-	-	4.25	1.20

Dimensions	Value (in mm)
C	2.50
G	3.60
X	1.40
X1	0.90
X2	0.90
Y	1.40
Y1	2.60
Y2	1.50
Y3	0.90

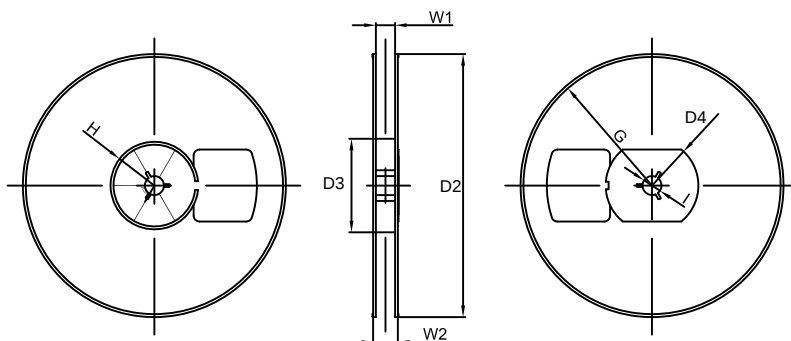
Tape & reel specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.60±0.20
D1	1.60±0.20
E	1.75±0.20
F	7.50±0.15
W	16.00±0.20
A0	6.30±0.20
B0	8.25±0.20
K0	2.60±0.20
T	0.23±0.10

13" Reel



D2	180.0±5.0
D3	60Min.
D4	R32.0±2.0
G	R86.5±2.0
H	R30.0±2.0
I	13.0±2.0
W1	13.20±2.0
W2	16.50±2.0

Quantity: 1000PCS